

TMP708 采用 SOT 封装的电阻可编程温度开关

1 特性

- 阈值精度：
 - 典型值 $\pm 0.5^{\circ}\text{C}$
 - 最大值 $\pm 3^{\circ}\text{C}$ (60°C 至 100°C)
- 由 1% 外部电阻设定的温度阈值
- 低静态电流：40 μA (典型值)
- 开漏、低电平有效输出级
- 可通过引脚选择的 10 $^{\circ}\text{C}$ 或者 30 $^{\circ}\text{C}$ 温度滞后
- $V_{\text{CC}} = 0.8\text{ V}$ 上指定的复位操作
- 电源范围：2.7V 至 5.5V
- 封装：5 引脚小外形尺寸晶体管 (SOT)-23

2 应用

- 计算机 (笔记本和台式机)
- 服务器
- 工业用和医疗用设备
- 存储区域网络
- 汽车用

3 说明

TMP708 是一款全集成式电阻可编程温度开关，其温度阈值仅由一个外部电阻在整个运行范围内进行设定。TMP708 提供一个低电平有效的开漏输出，可由电压介于 2.7V 至 5.5V 范围内的电源供电。

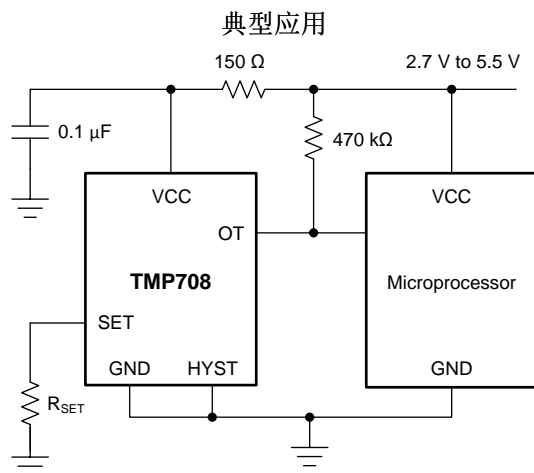
温度阈值精度通常为 $\pm 0.5^{\circ}\text{C}$ ，最大值为 $\pm 3^{\circ}\text{C}$ (60°C 至 100°C)。静态消耗电流的典型值为 40 μA 。可通过选择引脚来确定 10 $^{\circ}\text{C}$ 或者 30 $^{\circ}\text{C}$ 的温度滞后。

TMP708 采用 5 引脚小外形尺寸晶体管 (SOT-23) 封装。

器件信息⁽¹⁾

器件型号	封装	封装尺寸 (标称值)
TMP708	SOT-23 (5)	2.90mm x 1.60mm

(1) 要了解所有可用封装，请见数据表末尾的封装选项附录。



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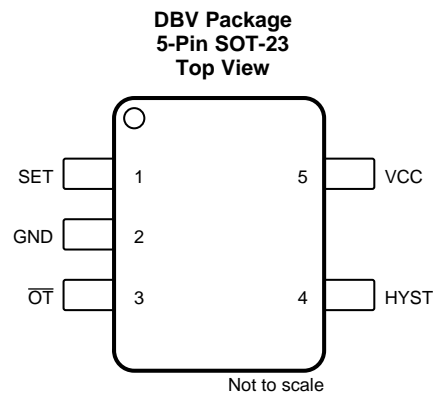
4 修订历史记录

注：之前版本的页码可能与当前版本有所不同。

Changes from Revision A (February 2012) to Revision B	Page
• 已添加 器件信息, ESD 额定值和建议运行条件表, 详细 说明, 应用和实施, 电源相关建议, 布局, 器件和文档支持以及机械、封装和可订购信息部分	1
• Deleted <i>Package and Ordering Information</i> table; information now available in package option addendum located at the end of this data sheet	2

Changes from Original (December 2011) to Revision A	Page
• 最新的阈值精度特性着着重号	1
• 更新了说明部分第二段中有关阈值精度的文本	1
• Updated temperature error parameter in the Electrical Characteristics	5

5 Pin Configuration and Functions



Pin Functions

PIN		TYPE	DESCRIPTION
NAME	NO.		
GND	2	Analog power	Device ground
HYST	4	Digital input	Hysteresis selection. For 10°C, HYST = VCC; for 30°C, HYST = GND.
\overline{OT}	3	Digital output	Open-drain, active low output
SET	1	Analog input	Temperature set point. Connect an external 1% resistor between SET and GND.
VCC	5	Analog power	Power-supply voltage (2.7 V to 5.5 V)

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) ⁽¹⁾

		MIN	MAX	UNIT
Voltage	Supply, V _{CC}	−0.3	6	V
	Input, SET and HYST	−0.3	V _{CC} + 0.3	
	Output, OT	−0.3	6	
Current	Input		20	mA
	Output		20	
Temperature	Operating, T _A	−40	125	°C
	Junction, T _J		150	
	Storage, T _{stg}	−65	150	

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

6.2 ESD Ratings

		VALUE	UNIT
V _(ESD)	Electrostatic discharge		V
	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±4000	
	Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾	±1000	
	Machine model (MM)	±200	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
 (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
V _{CC}	Supply voltage	2.7		5.5	V
T _A	Operating temperature	0		125	°C

6.4 Thermal Information

THERMAL METRIC ⁽¹⁾		TMP708	UNIT
		DBV (SOT-23)	
		5 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	217.9	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	86.3	°C/W
R _{θJB}	Junction-to-board thermal resistance	44.6	°C/W
ψ _{JT}	Junction-to-top characterization parameter	4.4	°C/W
ψ _{JB}	Junction-to-board characterization parameter	43.8	°C/W
R _{θJC(bot)}	Junction-to-case (bottom) thermal resistance	N/A	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

6.5 Electrical Characteristics

at $T_A = 0^\circ\text{C}$ to 125°C and $V_{CC} = 2.7\text{ V}$ to 5.5 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
POWER SUPPLY						
I_{CC}	Supply current	$V_{CC} = 5\text{ V}$		40	55	μA
		$V_{CC} = 2.7\text{ V}$		40	55	μA
TEMPERATURE						
T_E	Temperature error	$T_A = 60^\circ\text{C}$ to 100°C		± 0.5	± 3	$^\circ\text{C}$
DIGITAL INPUT (HYST)						
V_{IH}	High-level input voltage		$0.7 \times V_{CC}$			V
V_{IL}	Low-level input voltage			$0.3 \times V_{CC}$		V
I_{ikg_in}	Input leakage current			1		μA
C_{IN}	Input capacitance			10		pF
ANALOG INPUT (SET)						
V_{IN}	Input voltage range		0		V_{CC}	V
DIGITAL OPEN-DRAIN OUTPUT (\overline{OT})						
$I_{(OT_SINK)}$	Output sink current	$V_{OT} = 0.3\text{ V}$	5	12		mA
$I_{ikg(OT)}$	Output leakage current	$V_{OT} = V_{CC}$		1		μA

TMP708

ZHCS769B – DECEMBER 2011 – REVISED DECEMBER 2016

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6.6 Typical Characteristics

at $T_A = 25^\circ\text{C}$ and $V_{CC} = 2.7\text{ V}$ to 5.5 V (unless otherwise noted)

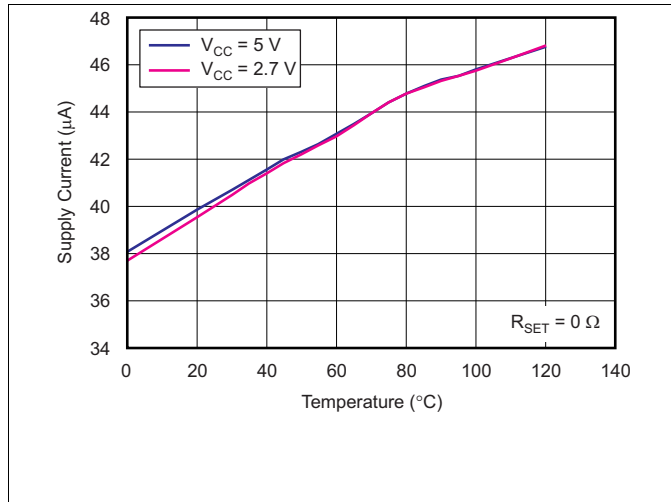


Figure 1. Supply Current vs Temperature

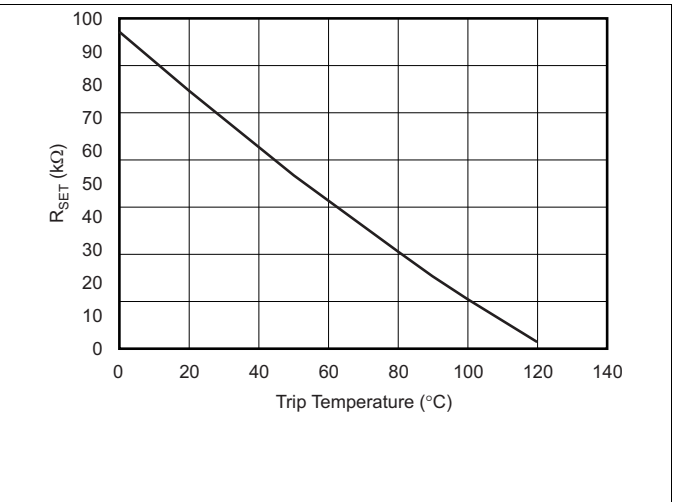


Figure 2. R_{SET} vs Trip Temperature

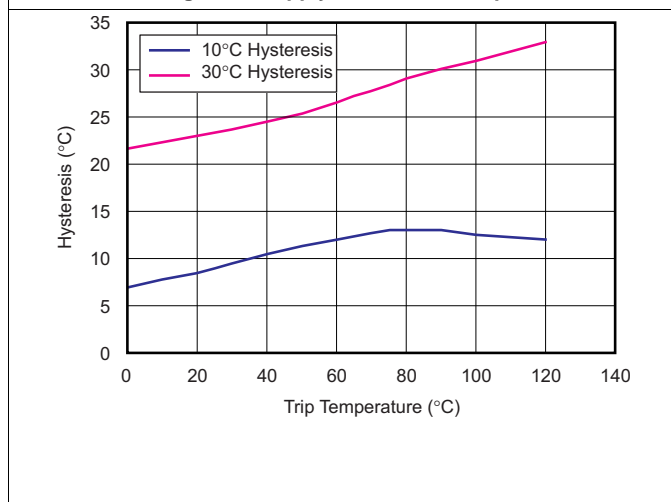


Figure 3. Hysteresis vs Trip Temperature

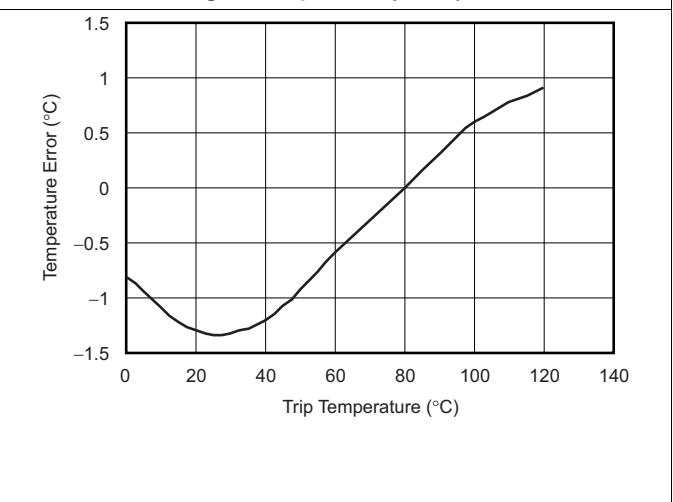


Figure 4. Temperature Error vs Trip Temperature

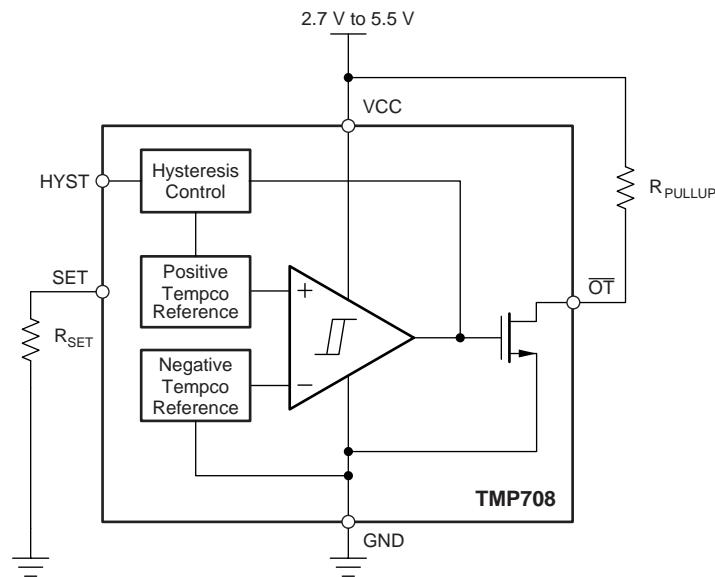
7 Detailed Description

7.1 Overview

The TMP708 is a fully-integrated, resistor-programmable temperature switch that incorporates two temperature-dependent voltage references and one comparator. One voltage reference exhibits a positive temperature coefficient (tempco), and the other voltage reference exhibits a negative tempco. The temperature at which both voltage references are equal determines the temperature trip point.

The [Functional Block Diagram](#) shows the comparator, the NFET open-drain device connected to the \overline{OT} pin, the positive tempco reference using the external R_{SET} resistor, the negative tempco reference, and the hysteresis control. The voltage of the positive tempco reference is controlled by external resistor R_{SET} .

7.2 Functional Block Diagram



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7.3 Feature Description

7.3.1 Temperature Switch

The TMP708 temperature threshold is programmable from 0°C to 125°C and is set by an external 1% resistor from the SET pin to the GND pin. The TMP708 has an open-drain, active-low output structure that easily interfaces with a microprocessor.

The TMP708 reaches the temperature trip point when the voltage from the positive tempco reference exceeds the voltage from the negative tempco reference. This difference causes the output of the comparator to switch from logic 0 to logic 1. The comparator output drives the gate of the NFET open-drain device, and pulls the voltage on the \overline{OT} pin from logic 1 to logic 0 under these conditions; in other words, the output *trips*. Furthermore, the logic 1 output from the comparator causes the hysteresis control to increase the voltage of the positive tempco reference by an amount set by the logic setting on the HYST pin (10°C for logic 1 on the HYST pin; 30°C for logic 0 on the HYST pin). Increase the voltage of the positive tempco reference after the TMP708 trips to stop the TMP708 from untripping (voltage on the \overline{OT} pin changing from logic 0 to logic 1) until the local temperature reduces by the amount set by the HYST pin. After the local temperature reduces, and the voltage from the positive tempco reference is less than the voltage from the negative tempco reference, the output of the comparator switches from logic 1 to logic 0. This condition causes the voltage on the \overline{OT} pin to change from logic 0 to logic 1 (device untrips).

7.3.2 Hysteresis Input

The HYST pin is a digital input that allows the input hysteresis to be set at either 10°C (when HYST = VCC) or 30°C (when HYST = GND). The hysteresis function keeps the \overline{OT} pin from oscillating when the temperature is near the threshold. Thus, always connect the HYST pin to either VCC or GND. Other input voltages on this pin can cause abnormal supply currents or a device malfunction.

7.3.3 Set-Point Resistor (R_{SET})

Set the temperature threshold by connecting R_{SET} from the SET pin to GND. The value of R_{SET} is determined using either [Figure 2](#) or [Equation 1](#):

$$R_{SET} \text{ (k}\Omega\text{)} = 0.0012T^2 - 0.9308T + 96.147$$

where

- T = temperature threshold in degrees Celsius. (1)

7.4 Device Functional Modes

The TMP708 device has a single functional mode. Normal operation for the TMP708 device occurs when the power-supply voltage applied across the VCC and GND pins is within the specified operating range of 2.7 V to 5.5 V.

8 Application and Implementation

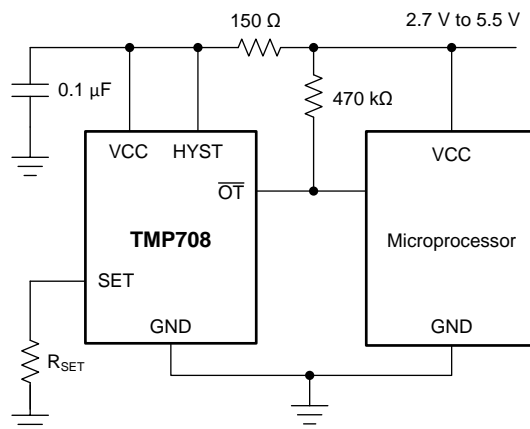
NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

The TMP708 device is simple to configure. The only external components that the device requires are a bypass capacitor and pullup resistor. Power-supply bypassing is strongly recommended. Use a 0.1- μ F capacitor placed as close as possible to the VCC supply pin. To minimize the internal power dissipation of the TMP708 family of devices, use a pullup resistor value greater than 10 k Ω from the OT pin to the VCC pin. See the [Hysteresis Input](#) section for hysteresis configuration, and the [Set-Point Resistor \(\$R_{SET}\$ \)](#) section for configuring the temperature threshold.

8.2 Typical Application



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Figure 5. Overtemperature Protection for a 60°C Trip Point

8.2.1 Design Requirements

For this design example, a 2.7-V to 5.5-V power supply, 60°C trip point, and 10°C hysteresis are used.

Typical Application (continued)

8.2.2 Detailed Design Procedure

Connect the HYST pin to VCC for 10°C hysteresis. For a 60°C temperature threshold, see the [Set-Point Resistor \(\$R_{SET}\$ \)](#) section to compute an ideal R_{SET} resistor value of 44.619 k Ω . Select the closest standard value resistor available; in this case, 44.2 k Ω . Use a 10-k Ω pullup resistor from the \overline{OT} pin to the VCC pin. To minimize power, a larger-value pullup resistor can be used, but must not exceed 470 k Ω . Place a 0.1- μ F bypass capacitor close to the TMP708 device in order to reduce noise coupled from the power supply.

8.2.3 Application Curves

Figure 6 shows an example of the hysteresis feature. The HYST pin is connected to VCC, so the TMP708 device is configured for 10°C of hysteresis. The device is configured for a 60°C trip temperature by the R_{SET} resistor value; therefore, the \overline{OT} output asserts low when the 60°C threshold is exceeded. The \overline{OT} output remains asserted low until the sensor reaches 50°C.

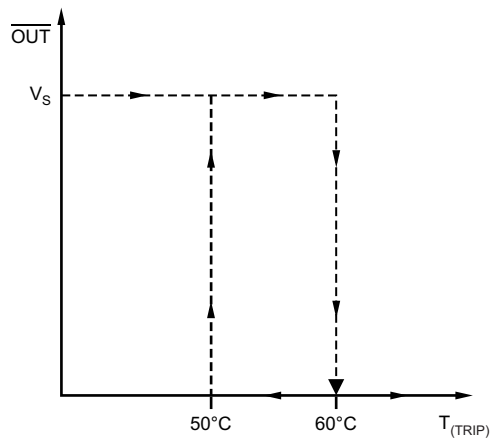


Figure 6. TMP708 Hysteresis Function

9 Power Supply Recommendations

The TMP708 low supply current and supply range allow this device to be powered from many sources. Any significant noise on the VCC pin can result in a trip-point error. Minimize this noise by low-pass filtering the device supply (V_{CC}) using a 150-Ω resistor and a 0.1-μF capacitor.

10 Layout

10.1 Layout Guidelines

The TMP708 is extremely simple to lay out. [Figure 7](#) shows the recommended board layout.

10.2 Layout Example

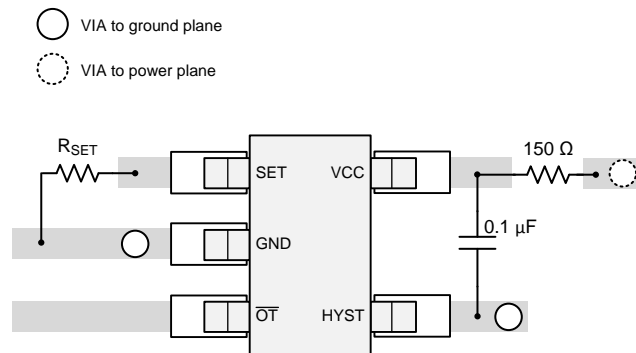


Figure 7. Recommended Layout

10.3 Thermal Considerations

The TMP708 quiescent current is typically 40 μA. The device dissipates negligible power when the output drives a high-impedance load. Thus, the die temperature is the same as the package temperature. In order to maintain accurate temperature monitoring, provide a good thermal contact between the TMP708 package and the device being monitored. The rise in die temperature as a result of self-heating is given by [Equation 2](#):

$$\Delta T_J = P_{DISS} \times \theta_{JA}$$

where

- P_{DISS} = power dissipated by the device.
- θ_{JA} = package thermal resistance. Typical thermal resistance for SOT-23 package is 217.9°C/W. (2)

To limit the effects of self-heating, keep the output current at a minimum level.

11 器件和文档支持

11.1 接收文档更新通知

如需接收文档更新通知，请访问 www.ti.com.cn 网站上的器件产品文件夹。点击右上角的提醒我 (Alert me) 注册后，即可每周定期收到已更改的产品信息。有关更改的详细信息，请查阅已修订文档中包含的修订历史记录。

11.2 社区资源

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ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能导致器件与其发布的规格不相符。

11.5 Glossary

SLYZ022 — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

12 机械、封装和可订购信息

以下页中包括机械、封装和可订购信息。这些信息是针对指定器件可提供的最新数据。这些数据会在无通知且不对本文档进行修订的情况下发生改变。欲获得该数据表的浏览器版本，请查阅左侧的导航栏。

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TMP708AIDBVR	Active	Production	SOT-23 (DBV) 5	3000 LARGE T&R	Yes	NIPDAU SN	Level-2-260C-1 YEAR	-40 to 125	SBI
TMP708AIDBVT	Obsolete	Production	SOT-23 (DBV) 5	-	-	Call TI	Call TI	-40 to 125	SBI

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF TMP708 :

- Automotive : [TMP708-Q1](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

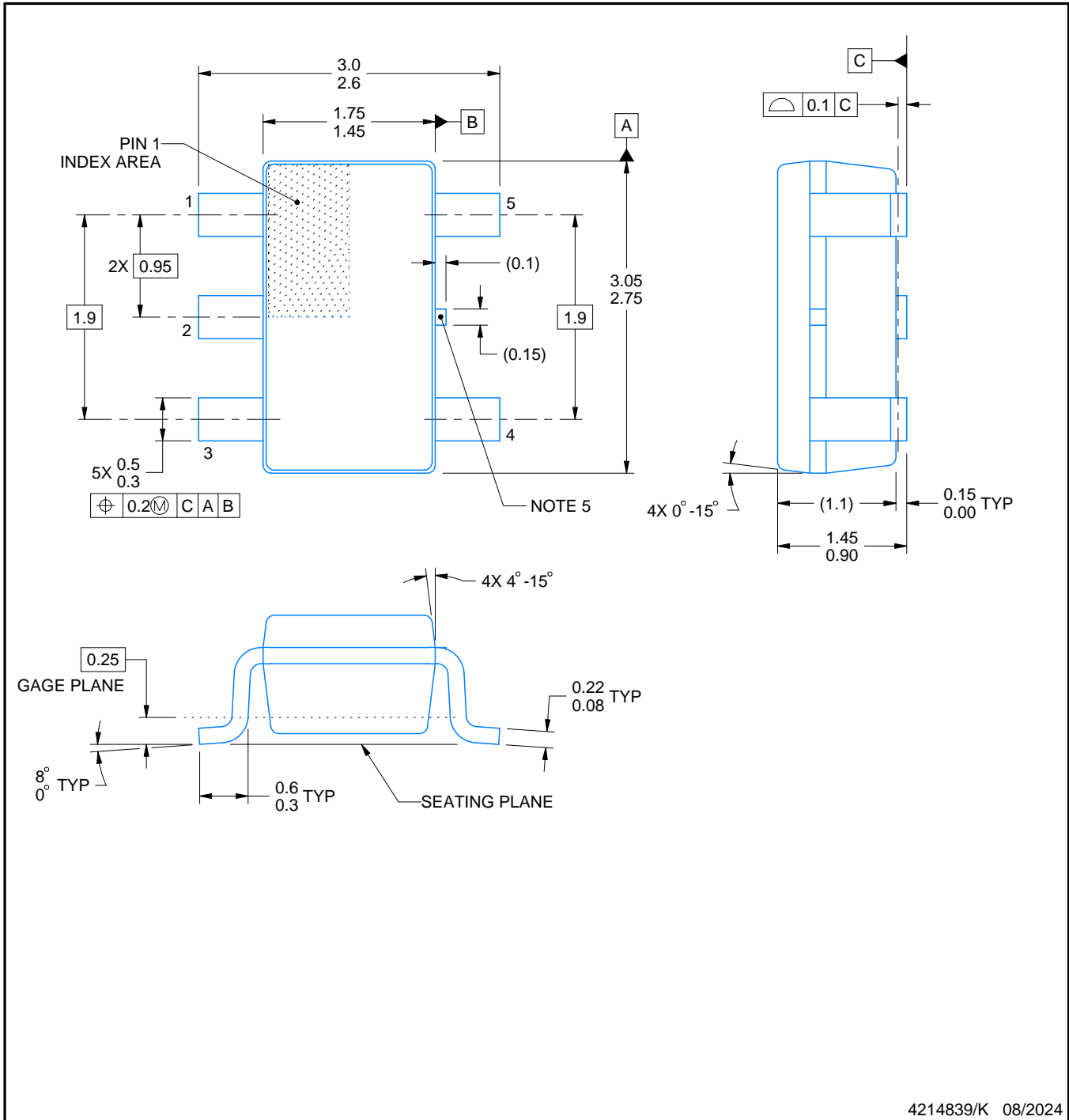

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TMP708AIDBVR	SOT-23	DBV	5	3000	180.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TMP708AIDBVR	SOT-23	DBV	5	3000	210.0	185.0	35.0



4214839/K 08/2024

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC MO-178.
4. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25 mm per side.
5. Support pin may differ or may not be present.

EXAMPLE BOARD LAYOUT

DBV0005A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:15X



SOLDER MASK DETAILS

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NOTES: (continued)

- Publication IPC-7351 may have alternate designs.
- Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DBV0005A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:15X

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NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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